

1/10/05

01-12-2005



102918561

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Charles W.C. Lin et al.
Assignee: Bridge Semiconductor Corporation
Title: SEMICONDUCTOR CHIP ASSEMBLY WITH BUMPED METAL PILLAR
Serial No.: 10/994,604 Filed: November 22, 2004
Examiner: Unknown Group Art Unit: 2812
Atty. Docket No.: BDG025

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ASSIGNMENT RECORDATION COVER SHEET

705 JAN 10 AM 9:00
OPR/FINANCE

Dear Sir:

Please record the attached original Assignment.

1. Name of conveying parties:

Charles W.C. Lin
Cheng-Lien Chiang

2. Name and address of receiving party:

Bridge Semiconductor Corporation
3rd Floor, 157 Li-Te Road
Peitou District
Taipei, Taiwan 112

3. Nature of conveyance:

Assignment

The execution date of the Assignment is November 22, 2004.

01/11/2005 ECDOPER 00000090 502178 10994604
01 FC:8021 40.00 DA

4. Application number(s) or patent number(s)

This Assignment is being filed for U.S. Application Serial No. 10/994,604 filed November 22, 2004.

5. Name and address of party to whom correspondence should be mailed:

David M. Sigmond
487 Blackfoot Street
Superior, Colorado 80027

(303) 554-8371

6. Total number of applications and patents involved: 1.

7. Total fee under 37 C.F.R. § 1.21(h): \$40.

8. Method of Payment:

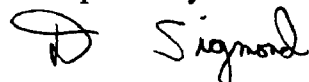
Charge the \$40 to Deposit Account No. 502178/BDG025 and charge any underpayment or credit any overpayment to this Account.

9. Statement and signature.

To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.

Total number of pages including cover sheet, attachments and document: 4.

Respectfully submitted,



David M. Sigmond
Attorney for Applicant
Reg. No. 34,013
(303) 554-8371
(303) 554-8667 (fax)

Date: Jan 4, 2005

ASSIGNMENT

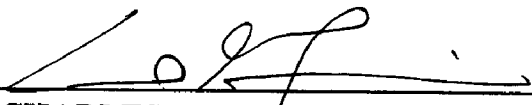
WHEREAS, we, CHARLES W.C. LIN of Singapore, and CHENG-LIEN CHIANG of Taipei, Taiwan, have invented a certain new and useful invention entitled SEMICONDUCTOR CHIP ASSEMBLY WITH BUMPED METAL PILLAR, for which an application for Letters Patent of the United States has been prepared for filing, said application being identified as Attorney Docket No. BDG025;

NOW THEREFORE, be it known that we, the said inventors, for and in consideration of certain good and valuable consideration, the sufficiency and receipt of which is hereby acknowledged, at the request of the assignee do sell, assign and transfer unto said assignee, BRIDGE SEMICONDUCTOR CORPORATION, a Taiwan Corporation having a place of business at 3rd Floor, 157 Li-Te Road, Peitou District, Taipei, Taiwan 112, its successors, legal representatives and assigns, the aforesaid application for the territory of the United States of America and all continuation, divisional, continuation-in-part and reissue applications, all patent applications in foreign countries, all applications pursuant to the Patent Cooperation Treaty, and all applications for extension filed or to be filed for the invention, and all Letters Patent, Invention Registrations, Utility Models, Extensions or Reissues, Reexaminations and other patent rights, obtained for the invention in the United States or any other country; we also assign any right, title or interest in and to the invention which has not already been transferred to the assignee; we warrant that we have made no assignment of the invention, application or patent therefor to a party other than BRIDGE SEMICONDUCTOR CORPORATION and we are under no obligation to make and shall not make any assignment of the invention, application, or patent therefor to any other party; and we further agree to cooperate with the assignee hereunder in obtaining, sustaining and enforcing of any and all such Letters Patent and patent rights and in confirming the assignee's exclusive ownership of the invention, without further consideration, but at the expense of said assignee.


The Commissioner of Patents is hereby authorized and requested to issue the Letters Patent solely in accordance with the terms of this Assignment to BRIDGE SEMICONDUCTOR CORPORATION, its successors, legal representatives and assigns, as the assignee of the entire right, title and interest therein.

IN WITNESS WHEREOF, the parties hereto have executed this Assignment as of the date indicated hereunder.

Date: Nov. 22, 2004

By: 
CHARLES W.C. LIN

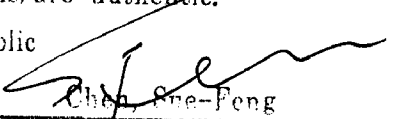
Date: Nov. 22, 2004

By: 
CHENG-LIEN CHIANG

NOTARY JURISDICTION: _____

Before me, a Notary Public in and for said Notary Jurisdiction, personally appeared CHARLES W.C. LIN, known to me to be the person whose name is subscribed to the foregoing instrument, and acknowledged to me that he executed the same for the purposes and considerations therein expressed.

093士院認003 Given under my hand and seal of office this _____ day of _____, 2004.

案號 001925	日期: NOV 22 2004
Case No.	Date
本文件 林文雄 之簽名或蓋章, 在台灣士林地方方法 院公證處認證。 公證人 城 素 芬	
Attested at the Notary Public Office of Taiwan Shihlin District Court, R.O.C., that the signature(s)/seal(s) of CHARLES W.C. LIN this document is/are authentic.	
Notary Public  Chen, Sue-Feng	

Notary Public

My Commission Expires: _____

NOTARY JURISDICTION: _____

Before me, a Notary Public in and for said Notary Jurisdiction, personally appeared CHENG-LIEN CHIANG, known to me to be the person whose name is subscribed to the foregoing instrument, and acknowledged to me that he executed the same for the purposes and considerations therein expressed.

Given under my hand and seal of office this _____ day of _____, 2004.

Notary Public

My Commission Expires: _____